JSCJ

MSDS Report

Report NO.: MG00001000047

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJD65SN10H
Package Type :	TO-251S

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.000%	0.44%
Lead Frame	Cu	7440-50-8	99.900%	49.95%
	Fe	7439-89-6	0.060%	
	P	7723-14-0	0.037%	
	Ag	7440-22-4	0.003%	
Die Attach	Lead	7439-92-1	92.500%	1.09%
	Tin	7440-31-5	5.000%	
	silver	7440-22-4	2.500%	
Wire1	Al	7429-90-5	99.990%	0.36%
	others	—	0.010%	
Wire2	Cu	7440-50-8	96.80%	0.69%
	Pd	7440-05-3	2.98%	
	Au	7440-57-5	0.22%	
Mold Compound	Epoxy resin A	Trade Secret	5.914%	47.08%
	Epoxy resin B	29690-82-2	3.870%	
	Phenol Resin	Trade Secret	2.198%	
	Silica(Amorphous) A	60676-86-0	80.508%	
	Silica(Amorphous) B	7631-86-9	6.880%	
	Carbon black	1333-86-4	0.630%	
Plating	Tin	7440-31-5	100.000%	0.39%